SDAS036D - APRIL 1982 - REVISED AUGUST 1995

- 3-State Buffer-Type Outputs Drive Bus Lines Directly
- Bus-Structured Pinout
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

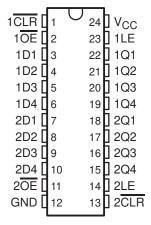
description

These dual 4-bit D-type latches feature 3-state outputs designed specifically for bus driving. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

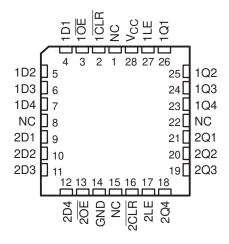
The dual 4-bit latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs in true form, according to the function table. When LE is low, the outputs are latched. When the clear (\overline{CLR}) input goes low, the Q outputs go low independently of LE. The outputs are in the high-impedance state when the output-enable (\overline{OE}) input is at a high logic level.

The SN54ALS873B and SN54AS873A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS873B and SN74AS873A are characterized for operation from 0°C to 70°C.

SN54ALS873B, SN54AS873A . . . JT PACKAGE SN74ALS873B, SN74AS873A . . . DW OR NT PACKAGE (TOP VIEW)



SN54ALS873B, SN54AS873A . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE (each latch)

	INPU	JTS		OUTPUT
ŌĒ	CLR	LE	D	Q
L	L	Χ	Х	L
L	Н	Н	Н	Н
L	Н	Н	L	L
L	Н	L	Χ	Q_0
Н	X	Χ	Χ	Z

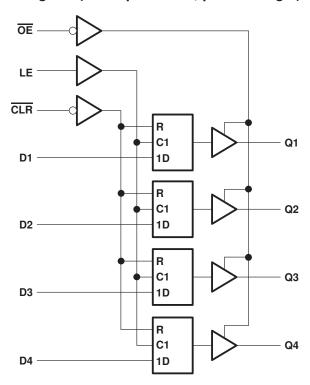
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logic symbol†

2 ΕN 10E 23 C1 1LE 1 С 1CLR 22 3 1D1 1D \triangleright ∇ 1Q1 4 21 1D2 1Q2 20 5 1D3 1Q3 19 6 1D4 1Q4 ΕN 2OE 14 2LE C1 13 2CLR С 18 1D 2D1 \triangleright ∇ 2Q1 17 8 2D2 2Q2 9 16 2Q3 2D3 15 10 2D4 2Q4

Pin numbers shown are for the DW, JT, and NT packages.

logic diagram (each quad latch, positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	5.5 V
Operating free-air temperature range, T _A : SN54ALS873B	–55°C to 125°C
SN74ALS873B	0°C to 70°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN54ALS873B SN74ALS873B					3B	LINUT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _C C	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			8.0	V
lOH	High-level output current			-1			-2.6	mA
lOL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEOT 0	TEST CONDITIONS			'3B	SN7	4ALS87	3B		
PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT	
VIK	V _{CC} = 4.5 V,	I _I = –18 mA			-1.2			-1.2	V	
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	<u>)</u>		V _{CC} -2	2			
VOH	V 45V	I _{OH} = -1 mA	2.4	3.3					V	
	V _{CC} = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.2			
V	V 45V	I _{OL} = 12 mA		0.25	0.4		0.25	0.4	.,	
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 24 mA					0.35	0.5	V	
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ	
lozL	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ	
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA	
lН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ	
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			- 0.2			- 0.2	mA	
I _O ‡	$V_{CC} = 5.5 V$,	V _O = 2.25 V	-20		-112	-30		-112	mA	
		Outputs high		11	21		11	21		
Icc	V _{CC} = 5.5 V	Outputs low		16	29		16	29	mA	
		Outputs disabled		20	31		20	31		

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		SN54AL	S873B	SN74AL	LIAUT			
			MIN	MAX	MIN	MAX	UNIT	
	Dulas dimetias	CLR low	15		15			
τ _W	Pulse duration	LE high	10		10		ns	
t _{su}	Setup time, data before LE↓		10		10		ns	
t _h	Hold time, data after LE↓		7		7		ns	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C (C _L R1 : R2 : T _A :	UNIT			
			SN54AL	S873B	SN74AL	S873B	
			MIN	MAX	MIN	MAX	
t _{PLH}	D	0	2	23	2	14	ns
^t PHL	D	Q	2	17	2	14	
^t PLH		0	8	31	8	22	
^t PHL	LE	Q	8	26	8	21	ns
^t PHL	CLR	Q	6	27	6	20	ns
^t PZH	ŌĒ	0	4	24	4	18	
^t PZL	OE	Q	4	23	4	18	ns
^t PHZ	ŌĒ	Q	2	12	2	10	20
^t PLZ	OE .	Q	2	30	2	15	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54AS873A	. −55°C to 125°C
SN74AS873A	0°C to 70°C
Storage temperature range	. −65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	54AS873	3A	SN	74AS87	3 A	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			8.0			0.8	V
ЮН	High-level output current			-12			-15	mA
lOL	Low-level output current			32			48	mA
TA	Operating free-air temperature	-55		125	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS			3A	SN	74AS87	3A	LIMIT
PARAMETER	TEST CO	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = – 18 mA			-1.2			-1.2	٧
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	<u> </u>		V _{CC} -2	2		
V_{OH}	V 45V	I _{OH} = -12 mA	2.4	3.2					V
	V _{CC} = 4.5 V	$I_{OH} = -15 \text{ mA}$				2.4	3.3		
V	V 45V	$I_{OL} = 32 \text{ mA}$		0.25	0.5				W
V _{OL}	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$					0.35	0.5	V
lozh	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
lozL	V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μΑ
lį	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
lН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			- 0.5			- 0.5	mA
I _O ‡	$V_{CC} = 5.5 \text{ V},$	V _O = 2.25 V	-30		-112	-30		-112	mA
_		Outputs high		68	110		68	110	
ICC	V _{CC} = 5.5 V	Outputs low		67	109		67	109	mA
		Outputs disabled		80	129		80	129	

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54AS	873A	SN74AS	S873A	LINUT	
			MAX	UNIT				
	CLR CLR	low	5		5			
t _W *	Pulse duration LE h	igh	6		5		ns	
t _{su} *	Setup time, data before LE \downarrow		2		2		ns	
t _h *	Hold time, data after LE↓	4.5		4.5		ns		

^{*} On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

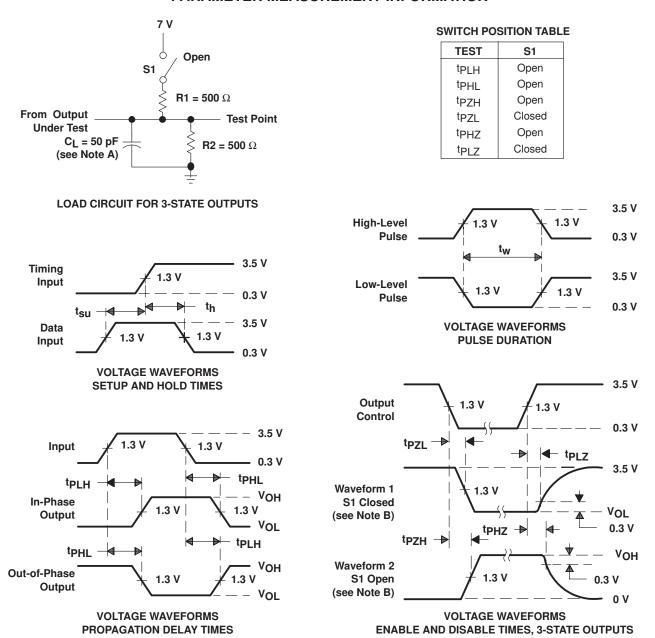
SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS SDAS036D - APRIL 1982 - REVISED AUGUST 1995

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R1 R2 T _A	UNIT			
			SN54A	S873A	SN74A	S873A	
			MIN	MAX	MIN	MAX	
t _{PLH}	D	0	3	12.5	3	9.5	ns
t _{PHL}	U	Q	3	8.5	3	7.5	
t _{PLH}		0	6	15.5	6	13	
t _{PHL}	LE	Q	4	9	4	7.5	ns
t _{PHL}	CLR	Q	3	10.5	3	9	ns
^t PZH	<u>OE</u>	0	2	8	2	6.5	
tPZL	OE	Q	4	11	4	10.5	ns
^t PHZ	<u>OE</u>	Q	2	8	2	7.5	ne
t _{PLZ}	OE	3	2	8.5	2	7.5	ns

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_O = 50 \Omega$, $t_r \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





29-May-2015

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84032013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84032013A SNJ54ALS 873BFK	Samples
8403201KA	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI	-55 to 125		
8403201LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403201LA SNJ54ALS873BJT	Samples
SN74ALS873BDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Samples
SN74ALS873BNT	LIFEBUY	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS873BNT	
SN74ALS873BNT3	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ADW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ADWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ANT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SNJ54ALS873BFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84032013A SNJ54ALS 873BFK	Samples
SNJ54ALS873BJT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403201LA SNJ54ALS873BJT	Samples
SNJ54AS873AFK	OBSOLETE	LCCC	FK	28		TBD	Call TI	Call TI	-55 to 125		
SNJ54AS873AJT	OBSOLETE	CDIP	JT	24		TBD	Call TI	Call TI	-55 to 125		
SNJ54AS873AW	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI	-55 to 125		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM



29-May-2015

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free** (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A:

Catalog: SN74ALS873B, SN74AS873A

Military: SN54ALS873B, SN54AS873A

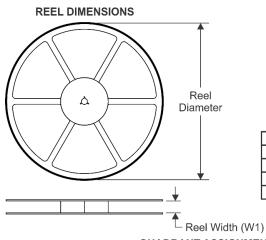
NOTE: Qualified Version Definitions:

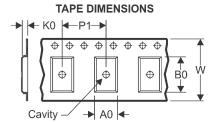
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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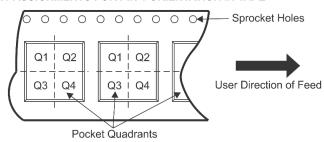
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

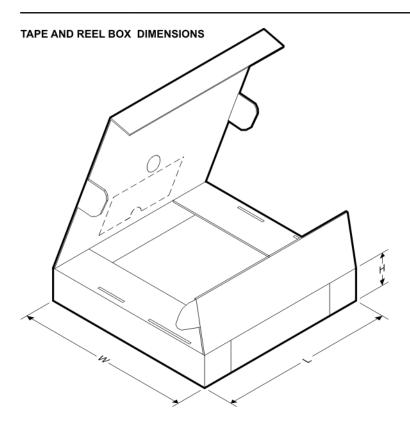
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS873BDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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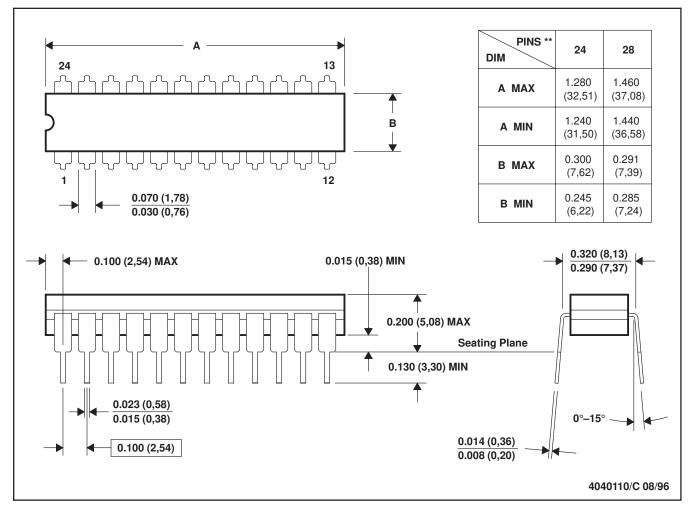
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS873BDWR	SOIC	DW	24	2000	367.0	367.0	45.0

JT (R-GDIP-T**)

24 LEADS SHOWN

CERAMIC DUAL-IN-LINE

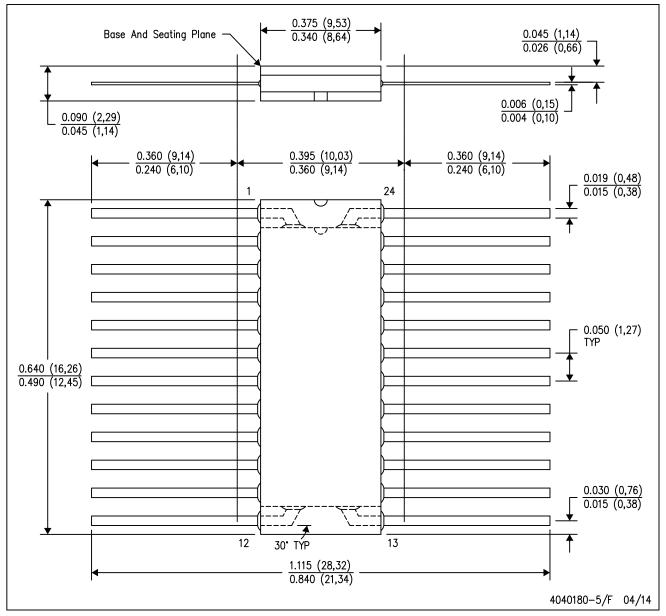


NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK



NOTES:

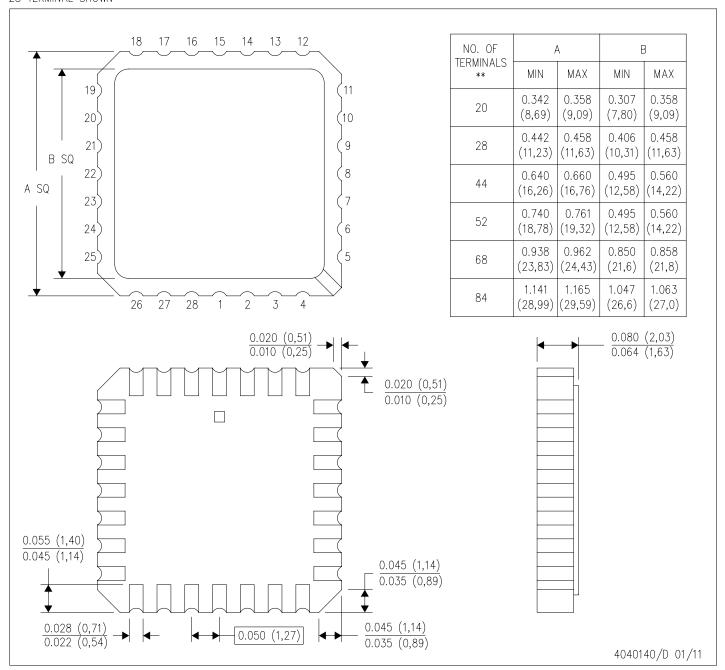
- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only. E. Falls within Mil—Std 1835 GDFP2—F20



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

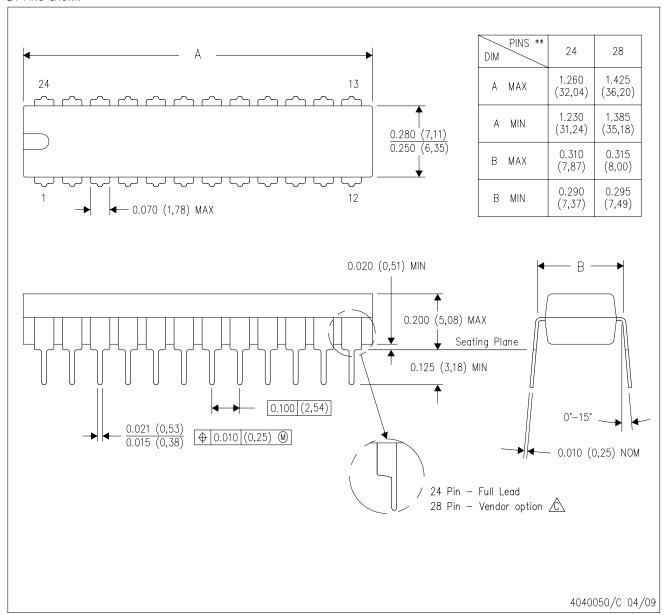
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

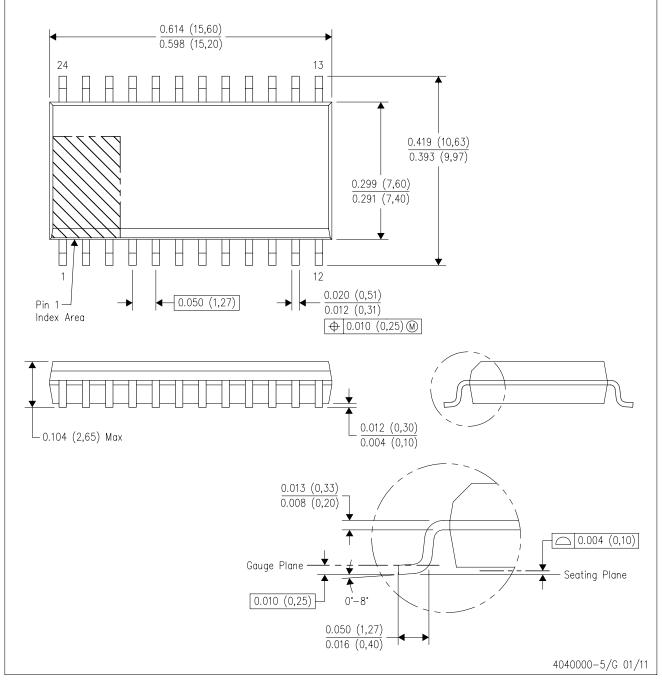
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

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